

AMENDMENTS TO THE SPECIFICATION:

Please replace paragraph [0001] with the following amended paragraph:

[0001] This Application is a Divisional Application of Application Serial No. 10/241,985 filed on September 12, 2002, currently pending, to Yaw S. Obeng, which, in turn, is a continuation-in-part of: U.S. Application No. 10/000,101, entitled, "THE SELECTIVE CHEMICAL-MECHANICAL POLISHING PROPERTIES OF A CROSS LINKED POLYMER AND SPECIFIC APPLICATIONS THEREFOR," to Yaw S. Obeng and Edward M. Yokley, filed on October 24, 2001; U.S. Application No. 09/998,471, entitled, "A METHOD OF INTRODUCING ORGANIC AND INORGANIC GRAFTED COMPOUNDS THROUGHOUT A THERMOPLASTIC POLISHING PAD USING A SUPERCRITICAL FLUID AND APPLICATIONS THEREFOR," to Edward M. Yokley and Yaw S. Obeng, filed on November 29, 2001; and U.S. Application No. 10/241,074, entitled, "A POLISHING PAD SUPPORT THAT IMPROVES POLISHING PERFORMANCE AND LONGEVITY," to Yaw S. Obeng and Peter Thomas filed on September 11, 2002, all of which are commonly assigned with the present invention, and incorporated by reference as if reproduced herein in their entirety.